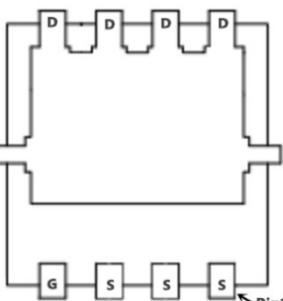
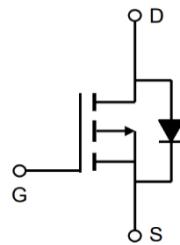


## Description

The AP30P06NF uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.



## General Features

$V_{DS} = -60V$   $I_D = -30A$

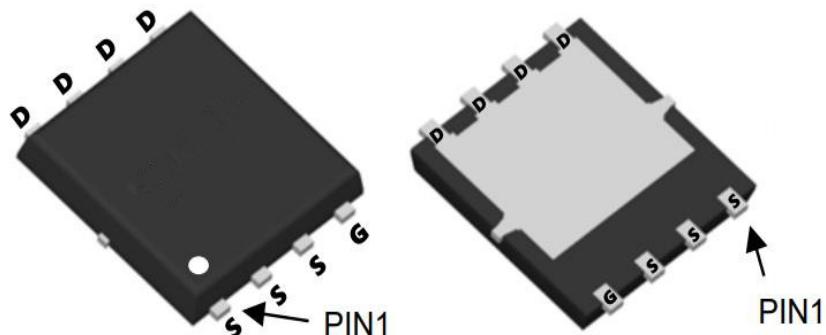
$R_{DS(ON)} < 35m\Omega$  @  $V_{GS} = -10V$  (Type: 28m $\Omega$ )

## Application

Lithium battery protection

Wireless impact

Mobile phone fast charging



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP30P06NF	PDFN5*6-8L	AP30P06NF XXX YYYY	5000

## Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

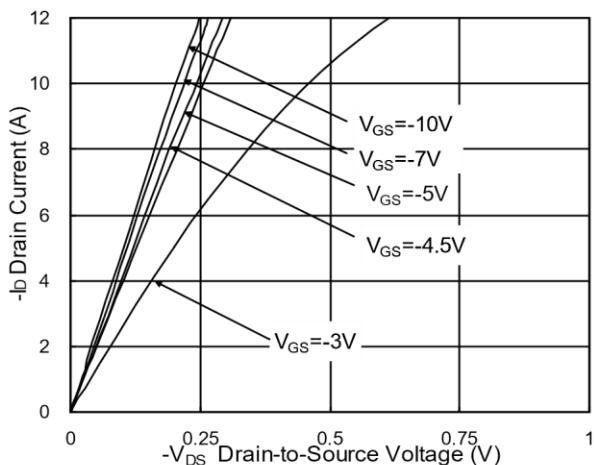
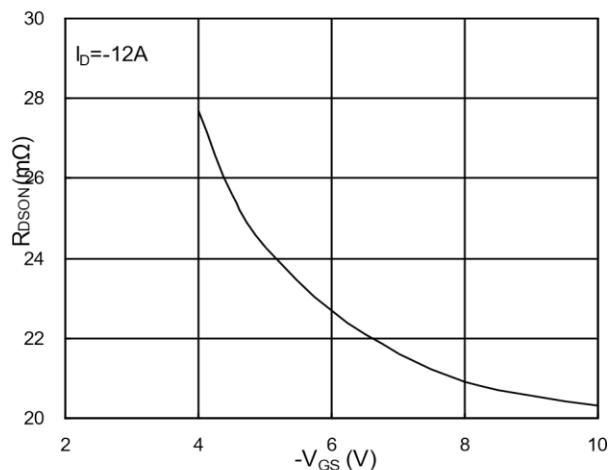
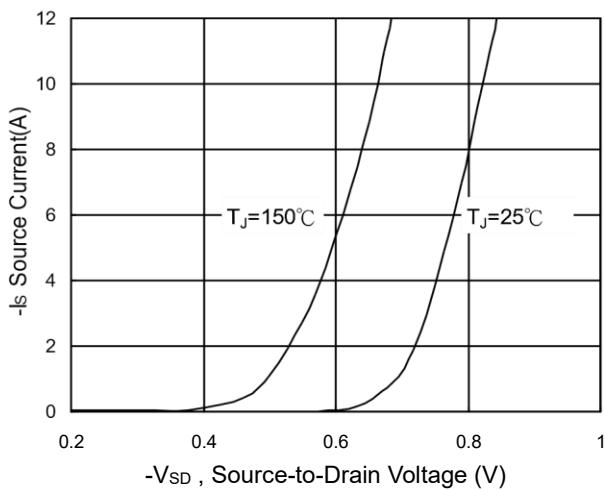
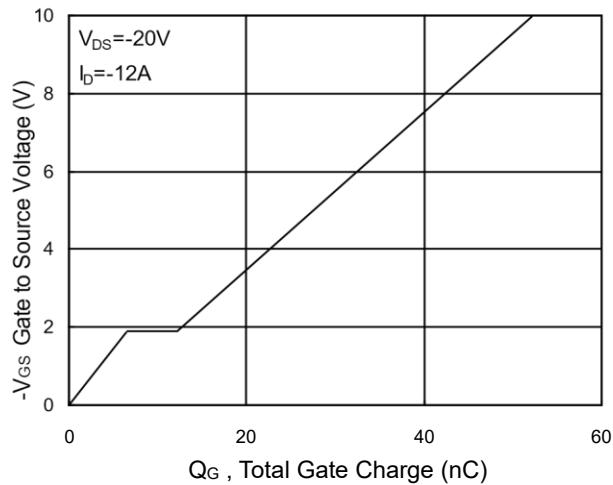
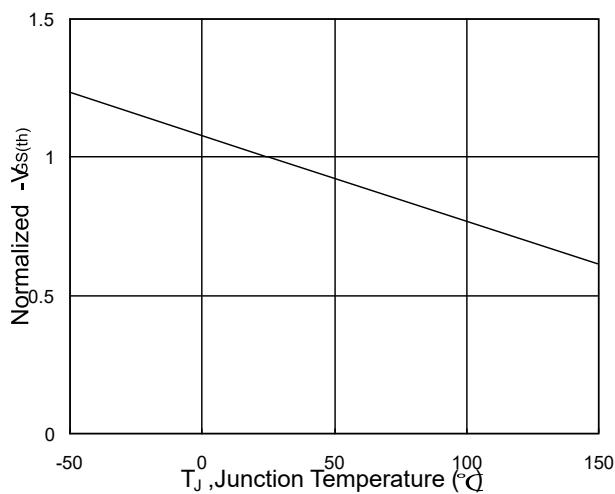
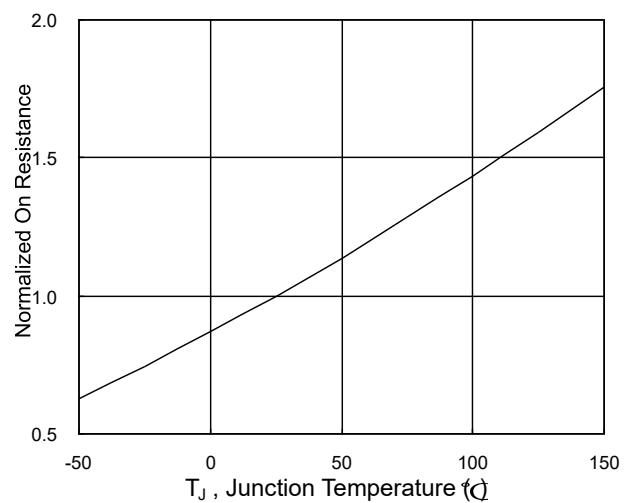
Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c=25^\circ C$	Continuous Drain Current, $-V_{GS} @ -10V^1$	-30	A
$I_D @ T_c=100^\circ C$	Continuous Drain Current, $-V_{GS} @ -10V^1$	-27	A
$IDM$	Pulsed Drain Current <sup>2</sup>	-85	A
$EAS$	Single Pulse Avalanche Energy <sup>3</sup>	113	mJ
$IAS$	Avalanche Current	47.6	A
$P_D @ T_c=25^\circ C$	Total Power Dissipation <sup>4</sup>	52.1	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	25	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	2.4	°C/W

**-60V P-Channel Enhancement Mode MOSFET**
**Electrical Characteristics ( $T_c=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-60	-68	---	V
$\Delta BVDSS/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	---	-0.035	---	$\text{V}/^\circ\text{C}$
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=-10\text{V}$ , $I_D=-10\text{A}$	---	28	35	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$ , $I_D=-8\text{A}$	---	35	42	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{Ds}$ , $I_D = -250\mu\text{A}$	-1.0	-1.6	-2.5	V
$\Delta V_{GS(\text{th})}$	$V_{GS(\text{th})}$ Temperature Coefficient		---	4.28	---	$\text{mV}/^\circ\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=-48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{DS}=-48\text{V}$ , $V_{GS}=0\text{V}$ , $T_J=55^\circ\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$ , $V_{DS}=0\text{V}$	---	---	$\pm 100$	nA
gfs	Forward Transconductance	$V_{DS}=-10\text{V}$ , $I_D=-18\text{A}$	---	23	---	S
R <sub>g</sub>	Gate Resistance	$V_{DS}=0\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	7	---	$\Omega$
Q <sub>g</sub>	Total Gate Charge (-4.5V)	$V_{DS}=-20\text{V}$ , $V_{GS}=-4.5\text{V}$ , $I_D=-12\text{A}$	---	25	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	6.7	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	5.5	---	
Td(on)	Turn-On Delay Time	$V_{DD}=-15\text{V}$ , $V_{GS}=-10\text{V}$ , $R_G=3.3\Omega$ , $I_D=-1\text{A}$	---	38	---	ns
T <sub>r</sub>	Rise Time		---	23.6	---	
Td(off)	Turn-Off Delay Time		---	100	---	
T <sub>f</sub>	Fall Time		---	6.8	---	
C <sub>iss</sub>	Input Capacitance	$V_{DS}=-15\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	---	3635	---	pF
C <sub>oss</sub>	Output Capacitance		---	224	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	141	---	
I <sub>s</sub>	Continuous Source Current <sup>1,5</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-35	A
ISM	Pulsed Source Current <sup>2,5</sup>		---	---	-70	A
VSD	Diode Forward Voltage <sup>2</sup>	$V_{GS}=0\text{V}$ , $I_S=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1	V

**Note :**

- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is  $VDD=-48\text{V}, VGS =-10\text{V}, L=0.1\text{mH}, IAS =-47.6\text{A}$
- 4、The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5、The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

**Typical Characteristics**

**Fig.1 Typical Output Characteristics**

**Fig.2 On-Resistance v.s Gate-Source**

**Fig.3 Forward Characteristics Of Reverse**

**Fig.4 Gate-Charge Characteristics**

**Fig.5 Normalized  $V_{GS(th)}$  v.s  $T_J$** 

**Fig.6 Normalized  $R_{DS(on)}$  v.s  $T_J$** 


## -60V P-Channel Enhancement Mode MOSFET

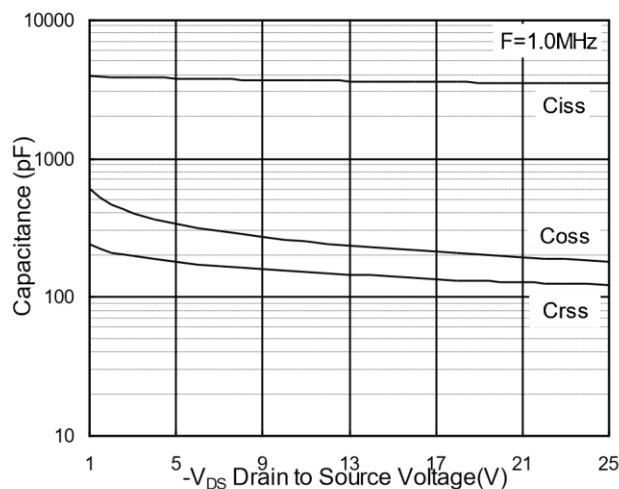


Fig.7 Capacitance

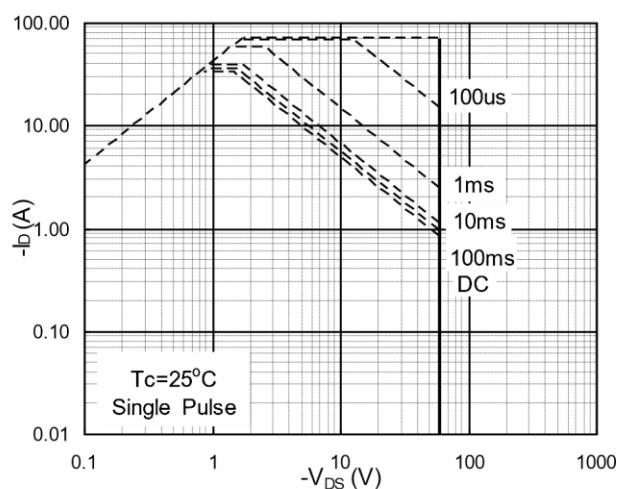


Fig.8 Safe Operating Area

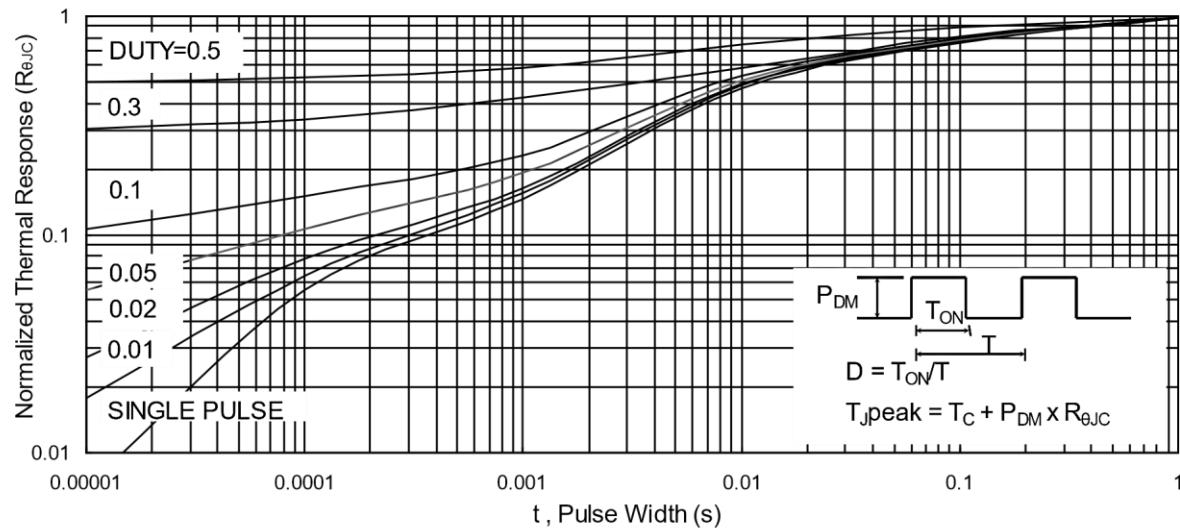


Fig.9 Normalized Maximum Transient Thermal Impedance

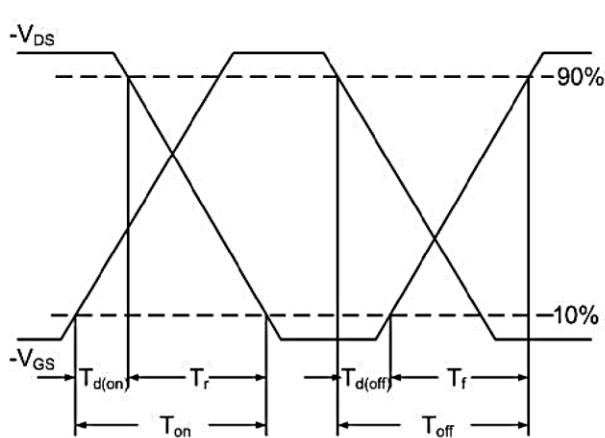


Fig.10 Switching Time Waveform

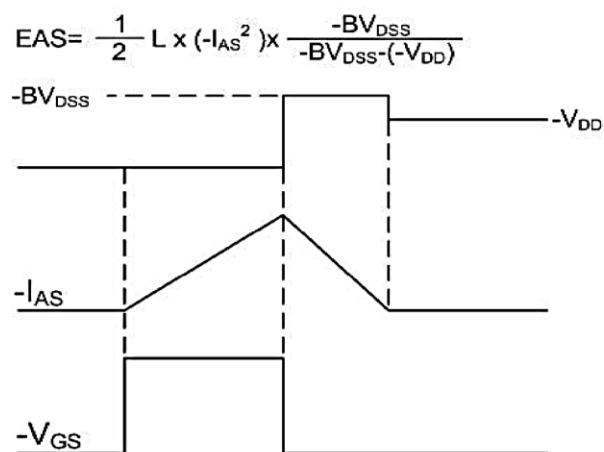
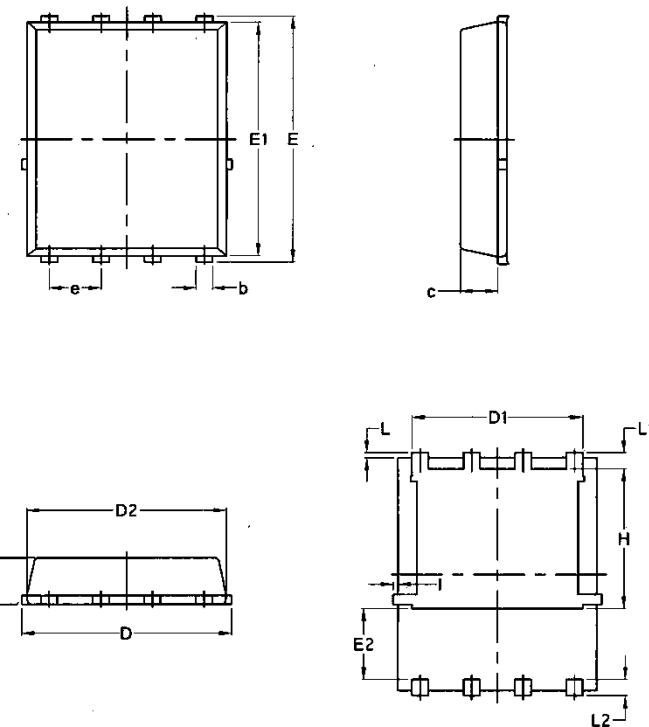


Fig.11 Unclamped Inductive Waveform

**Package Mechanical Data-DFN5\*6-8L-JQ Single**


Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070